GALXYL® DIMER FOR PARYLENE CONFORMAL COATINGS



GALXYL® DIMER

GALXYL dimer, manufactured by Galentis S.r.L., is the raw material used in the Parylene conformal coating process. The unique nature of the material's deposition enables the resultant Parylene coatings to reliably protect, preserve and insulate a wide variety of substrates.

Parylene coatings are ultra-thin and truly conformal and have been protecting components and devices in the aerospace, electronics, industrial, medical and military industries for decades. Due to their unique vapor deposition process, Parylene coatings protect even seemingly inaccessible areas, resulting in complete encapsulation of a substrate. Parylene films created with GALXYL C dimer are MIL-I-46058C and IPC-CC-830 approved and are an ideal solution for medical implantables due to their USP XXII, Class VI biocompatibility rating.

EXCELLENT PROPERTIES AND PROTECTION

Parylene films created using GALXYL dimer offer many useful and beneficial properties to design engineers:

- Ultra-thin coatings ranging from 0.01 to 100 microns
- Lightweight, stress-free
- Completely uniform; no pooling or edge-effects
- Optically clear
- Unrivaled barrier properties with low permeability to gases and moisture
- Superior dielectric strength for electrical insulation
- Barrier resistance to acids, alkalis and solvents
- Biocompatibility
- Thermal stability up to 275°C (in the absence of oxygen)
- Cryogenic resistance down to -200°C
- Resistant to fungus and bacteria
- Dry film lubricity
- Increases mechanical strength of underlying components





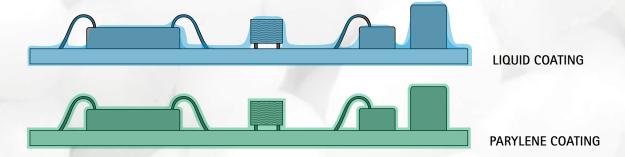




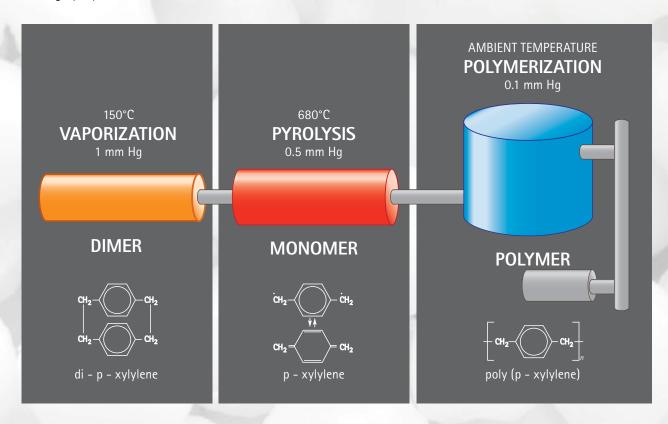
FOR PARYLENE CONFORMAL COATINGS

DEPOSITION PROCESS

Parylene coatings are formed with GALXYL dimer via a deposition process that occurs at the molecular level. As a result, any sharp edges, crevices, pores and recessed areas on a substrate are all covered by a uniform thickness of Parylene film. The coating is formed in-situ on the substrate surface, regardless of the substrate's complexity.



The vapor deposition polymerization process of GALXYL Parylene N film is illustrated below. The process begins as GALXYL dimer vaporizes under vacuum at 150–170°C. The vapor then passes through the pyrolysis zone (680°C) where a monomer vapor is formed. When the monomer molecules enter the deposition chamber (at 0.1 mm Hg), they find the substrate at ambient temperature. Condensation of the reactive monomer occurs on the substrate and, since molecules are very close to one another, polymerization simultaneously takes place. The resulting polymer is linear and highly crystalline.



GALXYL® DIMER FORMS PARYLENE FILMS THAT FEATURE OUTSTANDING PROPERTIES

TYPICAL PROPERTIES OF GALXYL FILMS **GALXYL N GALXYL C** VOLUME RESISTIVITY 101 Data recorded following appropriate ASTM method. GALXYL N TYPICAL PHYSICAL AND MECHANICAL PROPERTIES 10¹¹ 6,500 10,000 Tensile strength, psi **GALXYL** C Tensile strength, MPa 45 69 101 Yield strength, psi 6,300 8.000 Yield strength, MPa 43 55 Tensile modulus, MPa 2,400 3,200 1014 Elongation at break, % 40 200 Yield elongation, % 2.5 2.9 Density, q/cm3 20 60 80 120 140 160 180 200 1.110 1.289 Temperature, °C Coefficient of friction: static 0.25 0.29 0.25 0.29 DIELECTRIC CONSTANT Water absorption (24 hr), % 0.01 0.06 Index of refraction, n_n²³ 1.661 1.639 5 TYPICAL ELECTRICAL PROPERTIES **GALXYL C** 7,000 5,600 Dielectric strength, short time (Volts/mil at 1 mil) Volume resistivity, 23°C, 50% RH (Ohm-cm) 1 x 10¹⁷ 6 x 10¹⁶ Surface resistivity, 23°C, 50% RH (Ohms) 1 x 10¹⁵ 1 x 10¹⁵ Dielectric constant: 60 Hz 2.65 3.15 1,000 Hz 2.65 3.10 1,000,000 Hz 2.65 2.95 Dissipation factor: 60 Hz 0.0002 0.020 100 150 200 Temperature, °C 0.0002 0.019 1,000 Hz 1,000,000 Hz 0.0006 0.013 DISSIPATION FACTOR TYPICAL BARRIER PROPERTIES 0.0600 GALXYL C Gas permeability* 0.0500 0.95 Nitrogen 7.7 0.0400 30 7.1 Oxygen 0.0300 Carbon dioxide 214 7.7 795 13 Hydrogen sulfide 0.0200 Sulphur dioxide 1890 11 0.0003 **GALXYL N** Chlorine 74 0.35 0.0002 Moisture vapor transmission** 1.50 0.50 0.0001 1 mil = 1/1000 in = 25.4 microns150 200 * cm3 - mil/100 in2 - 24 hr - atm (23°C) Temperature, °C ** g - mil/100 in² - 24 hr, 37°C, 90% RH TYPICAL THERMAL PROPERTIES Melting temperature, °C 410 290 Linear coefficient of expansion, 10-5/°C 6.9 3.5

Exclusive North American Distributor:



Thermal conductivity, 10⁻⁴ (cal/sec) / (cm² • °C/cm)

ADVANCED COATING

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3



